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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kloster, et al.

Serial No.: 09/820,079

Filed: July 31, 2002

For: STRUCTURE IN A  
MICROELECTRONIC DEVICE  
INCLUDING A BI-LAYER FOR A  
DIFFUSION BARRIER AND AN  
ETCH STOP LAYER

Examiner: Thomas J. Magee

Group Art Unit: 2811

Attorney Docket No.: 42390.P11026

CERTIFICATE OF MAILING

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AMENDMENT

Hon. Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the July 31, 2002 Office Action, with the time for response having been  
extended by one-month, please consider the following remarks: